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TECHNOLOGY CENTER 2800

PATENT APPLICATION
RESPONSE UNDER 37 CFR §1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER ART UNIT 2811

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Kazuo TANAKA

Group Art Unit: 2811

Application No.: 09/586,963

Examiner: C. Nguyen

Filed: June 5, 2000

Docket No.: 039894.01

For: A SEMICONDUCTOR DEVICE AND METHOD FOR MAKING THE SAME
THAT PROVIDE ARRANGEMENT OF A CONNECTING REGION FOR AN
EXTERNAL CONNECTING TERMINAL (AS AMENDED)

AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the Office Action dated January 23, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claim 2 as follows:

2. (Four Times Amended) A semiconductor device including a bonding pad, wherein the bonding pad is a multiple wiring layer structure, the bonding pad comprising:
- a first conductive layer connected to a conductive member for external connection;
 - a second conductive layer disposed below said first conductive layer, the second conductive layer having a plurality of openings;

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a third conductive layer disposed below said second conductive layer;
a first insulating interlayer disposed between said first conductive layer and said second conductive layer;
at least one first through hole provided in said first insulating interlayer;
a fourth conductive layer filling said at least one first through hole;
a second insulating interlayer disposed between said second conductive layer and said third conductive layer;
at least one second through hole provided in said second insulating interlayer the said at least one first through hole disposed substantially directly above said at least one second through hole; and
a fifth conductive layer filling said at least one second through hole, wherein said first insulating interlayer and said second insulating interlayer are connected to each other through said openings of said second conductive layer, and a contiguous section of said first insulating interlayer with said second insulating interlayer is, thereby, formed between said first conductive layer and said third conductive layer.

REMARKS

Claims 2-8, 12-14 and 21 are pending. By this Amendment, claim 2 is amended.

Entry of the amendments is proper under 37 C.F.R. §1.116 since the amendments: (a) place the application in condition for allowance for the reasons discussed herein; (b) do not raise any new issue requiring further search and/or consideration since the amendments merely amplify issues discussed throughout prosecution; (c) do not present any additional claims without canceling a corresponding number of finally rejected claims; and (d) place the application in better form for appeal, should an appeal be necessary. The amendments are necessary and were not earlier presented because they are made in response to arguments raised in the final rejection. Entry of the amendments is thus respectfully requested.